

Title (en)
FILM ARRANGEMENT WITH INCREASED TEMPERATURE RESISTANCE

Title (de)
FOLIENANORDNUNG MIT ERHÖHTER TEMPERATURBESTÄNDIGKEIT

Title (fr)
AGENCEMENT DE FEUILLES AVEC UNE PLUS GRANDE RÉSISTANCE THERMIQUE

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Application
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Abstract (en)
[origin: WO2011147835A1] An embodiment of the invention relates to a film arrangement (1) with a temperature resistance of up to at least 70 °C, comprising - at least one biologically degradable base layer (5), which comprises a polyhydroxycarboxylic acid or starch, with a proportion of at least 50 wt.% of the film arrangement, said base layer having a temperature resistance of no more than 60 °C, and - at least one first temperature-resistant film layer (10) that comprises a polymer that is different from the base layer, said temperature-resistant film layer having a glass transition temperature of at least 70 °C, and/or a crystallization degree of at least 10% and a melting point of at least 70 °C. Such a film arrangement has an increased temperature resistance with respect to the biologically degradable base layer (5) but still has a sufficient degree of biological degradability and compostability as a result of the base layer.

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